

ABSTRACT OF THE DISCLOSURE

The invention relates to a viscosity reducible radiation curable composition comprising at least one radiation curable component and a filler, wherein the composition has the properties i) a yield stress value of $< 1100 \text{ Pa}$, ii) a viscosity (at a shear rate of 1 sec^{-1}) between 1 and $1500 \text{ Pa}\cdot\text{sec}$, and iii) a filler settling speed less than 0.3 mm/day .